



Material Content Data Sheet



Sales Product Name		BSS138N H6327		Issued		13. August 2019		
MA#		MA001233710						
Package		PG-SOT23-3-5		Weight*		9.32 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	tin	7440-31-5	0.002	0.02		222	
	noble metal	gold	7440-57-5	0.008	0.09		860	
	inorganic material	silicon	7440-21-3	0.091	0.97	1.08	9745	10827
leadframe	inorganic material	silicon	7440-21-3	0.001	0.01		65	
	non noble metal	titanium	7440-32-6	0.003	0.03		323	
	non noble metal	chromium	7440-47-3	0.009	0.10		969	
	non noble metal	copper	7440-50-8	3.000	32.18	32.32	321774	323131
wire	non noble metal	copper	7440-50-8	0.008	0.08	0.08	832	832
encapsulation	organic material	carbon black	1333-86-4	0.058	0.62		6187	
	plastics	epoxy resin	-	1.240	13.30		133012	
	inorganic material	silicondioxide	60676-86-0	4.471	47.95	61.87	479461	618660
leadfinish	non noble metal	tin	7440-31-5	0.150	1.60	1.60	16048	16048
plating	noble metal	silver	7440-22-4	0.284	3.05	3.05	30502	30502
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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